

PLATAMID® HX 2620 POWDER

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Copolyamide Hot Melt Adhesive / Textile Applications

Platamid® HX 2620 Powder is a low melt viscosity copolyamide adhesive powder for the production of fusible interlinings. Platamid® HX 2620 Powder offers good laundry resistance and good steam resistance at low/medium fusing conditions.

性能	干 / 已调节	单位	测试标准
流变性能			
熔体体积流动速度	41.5 / *	cm ³ /10min	ISO 1133
温度	150 / *	°C	-
	302 / *	°F	-
载荷	2.16 / *	kg	-
	4.76 / *	lb	-
热性能			
熔融温度, 10°C/min	124 / *	°C	ISO 11357-1/-3

AVAILABLE GRADES

This grade is available in different grain sizes:

- Platamid® HX 2620 PA80 (0-80 µm paste dot)
- Platamid® HX 2620 PRA 170 (0-170 µm double dot)

PACKAGING

- Platamid® HX 2620 PA80 and Platamid® HX 2620 PRA 170 are delivered in 20 kg sealed bags.

SHELF LIFE

Two years from the date of delivery. For any use above this limit, please refer to our technical services.

加工方法	
Scattering, Paste, Double Dot	
供货形式	
粉料	
特殊性能	
Adhesive	
地区供应	
北美, 欧洲, 亚太, 中南美洲, 中东/非洲	